



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB117N20NFD		<b>Issued</b>		24. January 2018		
<b>MA#</b>		MA001158660						
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1567.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.562	1.12	1.12	11203	11203
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		194	
	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	copper	7440-50-8	304.026	19.39	19.42	193931	194183
wire	non noble metal	aluminium	7429-90-5	10.872	0.69	0.69	6935	6935
encapsulation	organic material	carbon black	1333-86-4	9.996	0.64		6376	
	plastics	epoxy resin	-	109.953	7.01		70137	
	inorganic material	silicondioxide	60676-86-0	546.435	34.86	42.51	348557	425070
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6160	6160
plating	non noble metal	nickel	7440-02-0	0.228	0.01		146	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	146
solder	noble metal	silver	7440-22-4	0.255	0.02		163	
	non noble metal	tin	7440-31-5	0.204	0.01		130	
	non noble metal	lead	7439-92-1	9.743	0.62	0.65	6215	6508
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		350	
	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	copper	7440-50-8	547.666	34.93	34.98	349339	349795
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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